## SN74AC11-Q1 TRIPLE 3-INPUT POSITIVE-AND GATE

SCLS523A - AUGUST 2003 - REVISED APRIL 2008

- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 2-V to 6-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 6 V
- Max t<sub>pd</sub> of 7.5 ns at 5 V

#### description/ordering information

(TOP VIEW) 1A 14 V<sub>CC</sub> 1B 2 13 1 1C 2A Пз 12 1 1Y 2B 4 11 ЗA 2C 10 🛛 3B 5 2Y 9 3C 6 GND 7 8 ЗY

**D PACKAGE** 

The 'AC11 device contains three independent

3-input AND gates. This device performs the Boolean function  $Y = A \bullet B \bullet C$  or  $Y = \overline{A} + \overline{B} + \overline{C}$  in positive logic.

T <sub>A</sub>	PACKAGE	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING								
–40°C to 85°C	SOIC – D	Tape and reel	SN74AC11IDRQ1	AC11IQ1								
-40 0 10 65 0	TSSOP – PW	Tape and reel	SN74AC11IPWRQ1	AC11IQ1								

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

	FUNCTION TABLE (each gate)											
	INPUTS		OUTPUT									
Α	В	С	Y									
Н	Н	Н	Н									
L	х	Х	L									
Х	L	Х	L									
х	х	L	L									



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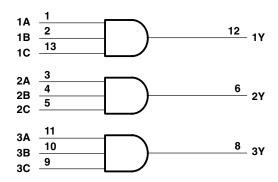


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#### logic diagram, each gate (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, V <sub>O</sub> (see Note 1)	–0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±200 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	
PW package	113°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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#### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2	6	V
		$V_{CC} = 3 V$	2.1		
V <sub>IH</sub>	High-level input voltage	$V_{CC} = 4.5 V$	3.15		V
		V <sub>CC</sub> = 5.5 V	3.85		
		$V_{CC} = 3 V$		0.9	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V		1.35	V
		V <sub>CC</sub> = 5.5 V		1.65	
VI	Input voltage		0	$V_{CC}$	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		$V_{CC} = 3 V$		-12	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 4.5 V		-24	mA
		$V_{CC} = 3 V$ $V_{CC} = 4.5 V$ $V_{CC} = 5.5 V$ $V_{CC} = 5.5 V$ $V_{CC} = 3 V$ $V_{CC} = 3 V$ $V_{CC} = 4.5 V$ $V_{CC} = 5.5 V$ ie age $V_{CC} = 3 V$ $V_{CC} = 5.5 V$ $V_{CC} = 3 V$ $V_{CC} = 5.5 V$ $V_{CC} = 3 V$ $V_{CC} = 3 V$ $V_{CC} = 3 V$ $V_{CC} = 3 V$ $V_{CC} = 5.5 V$ it on rise or fall rate ree-air temperature		-24	
		$V_{CC} = 3 V$		12	
l <sub>OL</sub>	Low-level output current	$V_{CC} = 4.5 V$		24	mA
		V <sub>CC</sub> = 5.5 V		24	
$\Delta t / \Delta v$	Input transition rise or fall rate			8	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C
			· · · · · ·		

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEAT CONDITIONS		Т	<sub>A</sub> = 25°C	;					
PARAMETER	TEST CONDITIONS	v <sub>cc</sub>	MIN	TYP	MAX	MIN	MAX	UNIT		
		3 V	2.9	2.99		2.9				
	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.49		4.4				
		5.5 V	5.4	5.49		5.4				
N.	I <sub>OH</sub> = -12 mA	3 V	2.56			2.46				
V <sub>OH</sub>	0.4	4.5 V	3.86			3.76		V		
	I <sub>OH</sub> = -24 mA	5.5 V	4.86			4.76				
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V								
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85				
		3 V		0.002	0.1		0.1			
	I <sub>OL</sub> = 50 μA	4.5 V		0.001	0.1		0.1	· V		
		5.5 V		0.001	0.1		0.1			
	I <sub>OL</sub> = 12 mA	3 V			0.36		0.44			
V <sub>OL</sub>		4.5 V			0.36		0.44			
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.44			
	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V								
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V					1.65			
l <sub>l</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1		±1	μA		
I <sub>CC</sub>	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			2		20	μA		
C <sub>i</sub>	VI = V <sub>CC</sub> or GND	5 V		2.6				pF		

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	Т	<sub>A</sub> = 25°C	;			
PARAMETER	(INPUT)	PUT) (OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
t <sub>PLH</sub>		V	1.5	5.5	9.5	1	10	
t <sub>PHL</sub>	A, B, or C	Y	1.5	5.5	8.5	1	9.5	ns

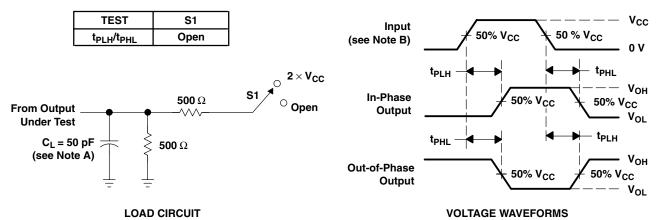
# switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$ (unless otherwise noted) (see Figure 1)

Γ	DADAMETED	FROM	то	T,	₄ = 25°C	;	MIN	МАХ	
	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX			UNIT
	t <sub>PLH</sub>		X	1.5	4	8	1	8.5	
	t <sub>PHL</sub>	A, B, or C	Ŷ	1.5	4	7	1	7.5	ns

#### operating characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	ТҮР	UNIT
$C_{\text{pd}}$	Power dissipation capacitance	$C_L = 50 pF$ , $f = 1 MHz$	20	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>1</sub> includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.

C. The outputs are measured one at a time with one input transition per measurement.

#### Figure 1. Load Circuit and Voltage Waveforms





10-Dec-2020

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AC11IDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11IQ1	Samples
SN74AC11IPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11IQ1	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

10-Dec-2020

#### OTHER QUALIFIED VERSIONS OF SN74AC11-Q1 :

- Catalog: SN74AC11
- Enhanced Product: SN74AC11-EP
- Military: SN54AC11

#### NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications



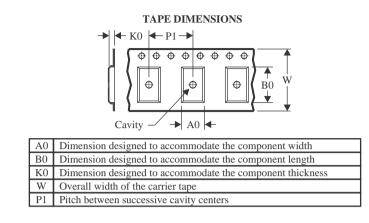
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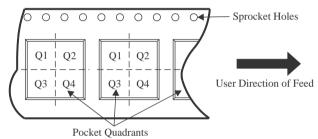
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### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



	Device	Package	Package	Pins	Γ
,	*All dimensions are nominal				

Device	•	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC11IPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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## PACKAGE MATERIALS INFORMATION

3-Jun-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC11IPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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